

#### **Technical Data Sheet**

### DOWSIL™ 3-8264 Encapsulant

DOWSIL™ 3-8264 Encapsulant is a two-part, 1:1 mix, black self-priming encapsulant

## Features & Benefits

- 1:1 mix ratio
- Flowable
- Self-priming
- Heat cure
- Good cure rate at moderate temperatures
- No additional priming step required
- Rapid cure at moderate temps can result in energy or cycle time savings
- Low viscosity enhances flow and fill in narrow spaces and around complex geometries

#### **Applications**

 Encapsulating applications requiring good primerless adhesion and lower heat cure temperatures

## Application Methods

- Automated metered mixing and dispensing
- Manual mixing

#### **Typical Properties**

Specification Writers: These values are not intended for use in preparing specifications.

Property	Unit	Result	
Viscosity (Part A or Base)	сР	3425	
	mPa-sec	3425	
	Pa-sec	3.4	
Viscosity (Part B or Catalyst)	сР	3275	
	mPa-sec	3275	
	Pa-sec	3.3	
Viscosity (Mixed)	сР	3350	
	mPa-sec	3350	
	Pa-sec	3.4	
Specific Gravity (Uncured)		1.33	
Working Time at 25°C (Pot Life - hours)	hr	5	
Heat Cure Time @ 70°C	minutes	150	
Heat Cure Time @ 100°C	minutes	30	
Durometer Shore A		44	

#### **Typical Properties (Cont.)**

Property	Unit	Result
Unprimed Adhesion - Lap Shear (AI)	psi	420
	MPa	2.9
	N/cm <sup>2</sup>	290
Dielectric Strength	volts/mil	425
	kV/mm	17
Dielectric Constant at 100 Hz		3.31
Dielectric Constant at 100 kHz		3.23
Volume Resistivity	ohm*cm	2.38 E+14
Dissipation Factor at 100 hz		0.007
Dissipation Factor at 100 kHz		< 0.001
Shelf Life at 25°C	months	9

## Mixing And De-Airing

Dow silicone encapsulants are supplied as two-part liquid component kits. When liquid components are thoroughly mixed, the mixture cures to a flexible elastomer, which is well suited for the protection of electrical and PCB system assembly. The 1:1 mix ratio is very robust in manufacturing environments and allows for some process and dispense equipment variation. Dow silicone encapsulants cure without exotherm at a constant rate regardless of sectional thickness or degree of confinement. Dow silicone elastomers require no post cure and can be placed in service immediately following the completion of the cure schedule. Standard silicone encapsulants require a surface treatment with a primer in addition to good cleaning for adhesion while primerless silicone encapsulants require only good cleaning.

### **Description**

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#### **Preparing Surfaces**

In applications requiring adhesion, priming will be required for the silicone encapsulants. See the Primer Selection Guide for the correct primer to use with a given product. For best results, the primer should be applied in a very thin, uniform coating and then wiped off after application. After application, it should be thoroughly air dried prior to application of the silicone elastomer. Additional instructions for primer usage can be found in the information sheets specific to the individual primers.

#### **Processing/Curing**

Thoroughly mixed Dow silicone encapsulant may be poured/dispensed directly into the container in which it is to be cured. Care should be taken to minimize air entrapment. When practical, pouring/dispensing should be done under vacuum, particularly if the component being potted or encapsulated has many small voids. If this technique cannot be used, the unit should be evacuated after the silicone encapsulant has been poured/dispensed. Dow silicone encapsulants may be either room temperature (25°C/77°F) or heat cured. Room temperature cure encapsulants may also be heat accelerated for faster cure. Ideal cure conditions for each product are given in the product selection table. Two-part condensation cure encapsulants should not be heat accelerated above 60°C (140°F).

## Pot Life And Cure Rate

Cure reaction begins with the mixing process. Initially, cure is evidenced by a gradual increase in viscosity, followed by gelation and conversion to a solid elastomer. Pot life is defined as the time required for viscosity to double after Parts A and B (base and curing agent) are mixed and is highly temperature and application dependent. Please refer to the data table.

### Useful Temperature Ranges

For most uses, silicone elastomers should be operational over a temperature range of -45 to 200°C (-49 to 392°F) for long periods of time. However, at both the low- and high temperature ends of the spectrum, behavior of the materials and performance in particular applications can become more complex and require additional considerations. For low-temperature performance, thermal cycling to conditions such as -55°C (-67°F) may be possible, but performance should be verified for your parts or assemblies. Factors that may influence performance are configuration and stress sensitivity of components, cooling rates and hold times, and prior temperature history. At the high-temperature end, the durability of the cured silicone elastomer is time and temperature dependent. As expected, the higher the temperature, the shorter the time the material will remain useable.

### Compatibility

Certain materials, chemicals, curing agents and plasticizers can inhibit the cure of addition cure adhesives. Most notable of these include: organotin and other organometallic compounds, silicone rubber containing organotin catalyst, sulfur, polysulfides, polysulfones or other sulfur containing materials, unsaturated hydrocarbon plasiticizers, and some solder flux residues. If a substrate or material is questionable with respect to potentially causing inhibition of cure, it is recommended that a small scale compatibility test be run to ascertain suitability in a given application. The presence of liquid or uncured product at the interface between the questionable substrate and the cured gel indicates incompatibility and inhibition of cure.

### Repairability

In the manufacture of electrical and PCB system assembly it is often desirable to salvage or reclaim damaged or defective units. With most non-silicone rigid potting/encapsulating materials, removal or entry is difficult or impossible without causing excessive damage to internal circuitry. Dow silicone encapsulants can be selectively removed with relative ease, any repairs or changes accomplished, and the repaired area repotted in place with additional product. To remove silicone elastomers, simply cut with a sharp blade or knife and tear and remove unwanted material from the area to be repaired. Sections of the adhered elastomer are best removed from substrates and circuitry by mechanical action such as scraping or rubbing and can be assisted by applying Dow OS fluids. Before applying additional encapsulant to a repaired device, roughen the exposed surfaces of the cured encapsulant with an abrasive paper and rinse with a suitable solvent. This will enhance adhesion and permit the repaired material to become an integral matrix with the existing encapsulant. Silicone prime coats are not recommended for adhering products to themselves.

#### Packaging Information

In general, Dow silicone 1:1 mix ratio encapsulants are supplied in nominal 0.45, 3.6, 18 and 200 kg (1, 8, 40, and 440 lb) containers, net weight. Dow silicone 10:1 mix ratio encapsulants are supplied in nominal 0.5, 5, 25 and 225 kg (1.1, 11, 55 and 495 lb) containers, net weight. Packaging options may vary by product.

## Usable Life And Storage

Shelf life is indicated by the "Use Before" date found on the product label. For best results, Dow silicone encapsulants should be stored at or below 25°C (77°F). Special precautions must be taken to prevent moisture from contacting these materials. Containers should be kept tightly closed and head or air space minimized. Partially filled containers should be purged with dry air or other gases, such as nitrogen.

## Health And Environmental Information

To support customers in their product safety needs, Dow has an extensive Product Stewardship organization and a team of product safety and regulatory compliance specialists available in each area.

For further information, please see our website, www.consumer.dow.com or consult your local Dow representative.

#### Limitations

This product is neither tested nor represented as suitable for medical or pharmaceutical uses.

## Handling Precautions

PRODUCT SAFETY INFORMATION REQUIRED FOR SAFE USE IS NOT INCLUDED IN THIS DOCUMENT. BEFORE HANDLING, READ PRODUCT AND SAFETY DATA SHEETS AND CONTAINER LABELS FOR SAFE USE, PHYSICAL AND HEALTH HAZARD INFORMATION. THE SAFETY DATA SHEET IS AVAILABLE ON THE DOW WEBSITE AT WWW.CONSUMER.DOW.COM, OR FROM YOUR DOW SALES APPLICATION ENGINEER, OR DISTRIBUTOR, OR BY CALLING DOW CUSTOMER SERVICE.

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